

AMENDMENTS TO THE CLAIMS

A detailed listing of all claims that are, or were, in the present application, irrespective of whether the claim(s) remains under examination in the application are presented below. The claims are presented in ascending order and each includes one status identifier. Those claims not cancelled or withdrawn but amended by the current amendment utilize the following notations for amendment: 1. deleted matter is shown by strikethrough for six or more characters and double brackets for five or less characters; and 2. added matter is shown by underlining.

1. (Cancelled)
2. (Currently Amended) The apparatus of claim ~~[[1]]~~ 7, wherein the first fluidic circuit includes a first applicator for directing fluid onto the interior surfaces of a wafer carrier, and the second fluidic circuit includes a second applicator for directing fluid onto the exterior surface of a wafer carrier.
3. (Original) The apparatus of claim 2, wherein the first and second applicators are sprayers.
4. (Previously Presented) The apparatus of claim 3, wherein the first and second sprayers are maneuverably disposed in the base portion.
5. (Original) The apparatus of claim 4, the base further comprising sidewalls, and a rear wall connected to the base portion.

6. (Original) The apparatus of claim 5, further comprising a cover sealingly connectable to the base and movable to permit access therein.

7. (Currently Amended) An apparatus for cleaning a semi-conductor wafer carrier having an interior surface and an exterior surface, the apparatus comprising:

a base portion having a first aperture and a second aperture, the base configured to support a wafer carrier about the first aperture ~~The apparatus of claim 1,~~ the base portion further comprising a third aperture, the base configured to support a wafer carrier door holding fixture in contact about the third aperture;

a first fluidic circuit; and,

a second fluidic circuit;

wherein the first fluidic circuit is configured to circulates fluid between the first aperture and the interior surfaces of a wafer carrier and the second fluidic circuit is configured to circulates fluid between the second aperture and the exterior surfaces of a wafer carrier and wherein, the base portion configured to substantially isolate the first fluidic circuit from the second fluidic circuit, and wherein the first fluidic circuit circulates fluid between the first and third apertures and the interior surfaces of a wafer carrier and a wafer carrier door holding fixture and the second fluidic circuit circulates fluid between the second aperture and the exterior surfaces of a wafer carrier and a wafer carrier door holding fixture to remove contaminants from the interior and exterior surfaces of a wafer carrier and a wafer carrier door.

8. (Cancelled)

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (Currently Amended) An apparatus for cleaning a semi-conductor wafer carrier having an interior surface and an exterior surface, and a wafer carrier door having an inside surface and an outside surface, the apparatus comprising:

a base ~~The apparatus of claim 10, wherein the base includes~~ including a fluid leakage detector disposed therein and one or more wash bays disposed in the base, each wash bay comprising a container cleaning assembly; and a door cleaning assembly, wherein a first cleaning fluid is used to clean the interior surface of the carrier and the inside surface of the door, and a second cleaning fluid is used to clean the exterior surface of the carrier and the outside surface of the door, the wash bays configured to substantially prevent communication of the second fluid with the first fluid.

14. (Currently Amended) The apparatus of claim ~~[[10]]~~ 13, wherein the container cleaning assembly includes a container fluid sprayer configured to permit selectable variable movement.

15. (Currently Amended) The apparatus of claim ~~[[10]]~~ 13, wherein the door cleaning assembly includes a door fluid sprayer configured to permit selectable variable movement.

16. (Currently Amended) An apparatus for cleaning a semi-conductor wafer carrier having an interior surface and an exterior surface, and a wafer carrier door having an inside surface and an outside surface, the apparatus comprising:

a base and one or more wash bays disposed in the base, each wash bay comprising a container cleaning assembly ~~The apparatus of claim 10, wherein~~ the container cleaning assembly ~~includes~~ including an ionizer for introducing ionized air into the interior surface of the wafer carrier; and a door cleaning assembly, wherein a first cleaning fluid is used to clean the interior surface of the carrier and the inside surface of the door, and a second cleaning fluid is used to clean the exterior surface of the carrier and the outside surface of the door, the wash bays configured to substantially prevent communication of the second fluid with the first fluid.

17. (Cancelled)

18. (Currently Amended) The apparatus of claim ~~[[10]]~~ 13, wherein the container cleaning assembly includes a ridge configured to substantially isolate the first fluidic circuit from the second fluidic circuit.

19. (Currently Amended) The apparatus of claim ~~[[10]]~~ 13, further comprising a closure releasably mounted to the base and configured to form a fluid tight seal at an interface between the closure and base.

20. (Original) The apparatus of claim 19, wherein the base includes a closure sensor for detecting a breach of the fluid tight seal during operation.

21. (Cancelled)

22. (Cancelled)

23. (Currently Amended) An apparatus for cleaning a semi-conductor wafer carrier having an interior surface and an exterior surface, the apparatus comprising: a base portion including a first fluidic circuit and a second fluidic circuit, a means for substantially isolating the first fluidic circuit from the second fluidic circuit ~~The apparatus of claim 22~~, wherein the means for isolating includes a means for mechanically isolating the first fluidic circuit from the second fluidic circuit.

24. (Currently Amended) An apparatus for cleaning a semi-conductor wafer carrier having an interior surface and an exterior surface, the apparatus comprising: a base portion including a first fluidic circuit and a second fluidic circuit, a means for substantially isolating the first fluidic circuit from the second fluidic circuit ~~The apparatus of claim 22~~, wherein the means for isolating includes a means for pneumatically isolating the first fluidic circuit from the second fluidic circuit.

REMARKS

Claims 1-7, 10, 13-16 and 18-24 are pending. By this Amendment, claims 2, 7, 13-16, 18-19, and 23-24 are amended, and claims 1, 8-12, 17 and 21-22 are, or remain, cancelled.

Applicant acknowledges the Examiner's comments in the Advisory Action of January 23, 2004. Further, Applicant appreciates the Examiner's indication during the telephone